




DOCUMENT CHANGE REQUEST

| | | | | | | | |
|--|---|------|--------|-------------------------------|--|--|--|
| DCR number | | 1569 | | Changes required for: General | | Originator: Steve Thacker | |
| Date: 2023/10/09 | | | | Date sent: 2023/04/03 | | Organisation: ESCC Executive Secretariat | |
| Status: IMPLEMENTED | | | | | | | |
| Title: | Preservation Packaging and Despatch of SCC Components | | | | | | |
| Number: | 20600 | | Issue: | 4 | | | |
| Other documents affected: | | | | | | | |
| | | | | | | | |
| Page: | | | | | | | |
| see current spec issue above | | | | | | | |
| Paragraph: | | | | | | | |
| See below | | | | | | | |
| Original wording: | | | | | | | |
| see current spec issue above | | | | | | | |
| Proposed wording: | | | | | | | |
| Changes to incorporate requirements for plastic encapsulated semiconductor components; see attached for details in Para 4.1.2 (with changes highlighted yellow). | | | | | | | |
| Justification: | | | | | | | |
| To add requirements for the newly published ESCC 9030 (as required by the 9000P Working Group) | | | | | | | |
| Attachments: | | | | | | | |
| esc20600iss_draft_5a_in_review.docx | | | | | | | |
| Modifications: | | | | | | | |
| N/A | | | | | | | |
| Approval signature: | | | | | | | |
|  | | | | | | | |
| Date signed: | | | | | | | |
| 2023-10-09 | | | | | | | |